GN04042N

GaAs N-Channel IC

High-frequency high-power output SP3T switch for Mobile Communication
The terminal for CDMA/PCS/GPS

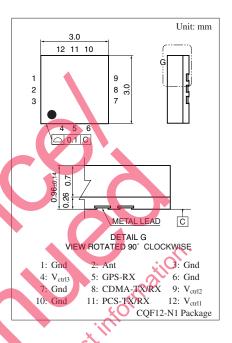
■ Features

Low insertion: LOSS = 0.27 dB (CDMA)
High isolation: ISO = 30 to 35 dB (CDMA)

• Small package

■ Absolute Maximum Ratings T_a = 25°C

Parameter		Symbol	Rating	Unit
Power dissipation		P_{D}	150	mW
Control current		$V_{ctrl(H)}$ - $V_{ctrl(L)}$	+5	V
Maximum	CDMA, PCS	P_{IN}	35	dBm
input power	GPS		20	
Operating ambient temperature		T _{opr}	-30 to +90	°C
Storage temperature		T _{stg}	-40 to +120	°C



■ Electrical Characteristics

• CDMA ($V_{ctrl(L)} = 0$ V, $V_{ctrl(H)} = 3.0$ V, f = 824 MHz to 894 MHz, $T_a = 25$ °C ± 3 °C)

Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Insertion loss	LOSS	ANT-C	$DMA_TX/RX (P_{IN} = 26 \text{ dBm})$		0.27	0.50	dB
Isolation	ISO		CS_TX/RX	25.0	30.0		dB
		(Corresp	ond of ANT-CDMA_TX/RX ON)				
		ANT-G	1.00	30.0	34.8		
		(Corresp	ond of ANT-CDMA_TX/RX ON)				
Voltage standing wave ratio *	VSWR	ANT-C	DMA_TX/RX		1.20	1.35	_
Input 0.1 dB compression	P _{IN(0.1 dB)}	ANT-C	DMA_TX/RX	30	33		dBm
2nd harmonics *	2f _O	ANT-C	$DMA_TX/RX (P_{IN} = 26 dBm)$		-76	-65	dBc
	0	Non-mo	odulation signal				
3rd harmonics *	$03f_{O}$	ANT-C	$DMA_TX/RX (P_{IN} = 26 dBm)$		-75	-68	dBc
	(e)	Non-mo	odulation signal				
Control current	I_{ctrl}	ANT-C	DMA_TX/RX		0.16	9.0	μΑ

Note) *: Designed specification

■ Electrical Characteristics (continued)

• PCS $(V_{ctrl(L)} = 0 \text{ V}, \ V_{ctrl(H)} = 3.0 \text{ V}, \ f = 1850 \text{ MHz to } 1990 \text{ MHz}, \ T_a = 25^{\circ}\text{C} \pm 3^{\circ}\text{C})$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Insertion loss *	LOSS	ANT-PCS_TX/RX ($P_{IN} = 24.0 \text{ dBm}$)		0.33	0.50	dB
Isolation *	ISO	ANT-CDMA_TX/RX	19.0	22.0		dB
		(Correspond of ANT-PCS_TX/RX ON)				
		ANT-GPS_RX	20.0	26.0		
		(Correspond of ANT-PCS_TX/RX ON)				
Voltage standing wave ratio *	VSWR	ANT-PCS_TX/RX		1.10	1.30	_
Input 0.1 dB compression *	P _{IN(0.1 dB)}	ANT-PCS_TX/RX	30	33		dBm
2nd harmonics *	2f _O	ANT-PCS_TX/RX ($P_{IN} = 24.0 \text{ dBm}$)		-76	-65	dBc
		Non-modulation signal				
3rd harmonics *	3f _O	ANT-PCS_TX/RX ($P_{IN} = 24.0 \text{ dBm}$)		-78	-74	dBc
		Non-modulation signal				
Control current *	I_{ctrl}	ANT-PCS_TX/RX		0.14	9.0	μΑ

Note) *: Designed specification

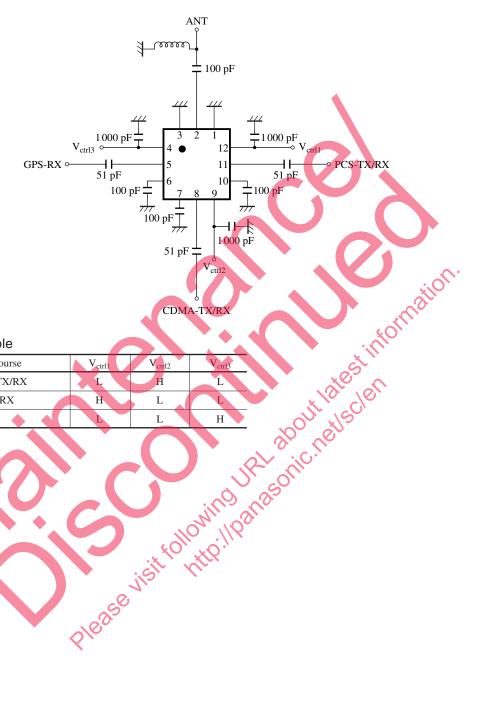
• GPS $(V_{ctrl(L)} = 0 \text{ V}, \ V_{ctrl(H)} = 3.0 \text{ V}, \ f = 1574 \text{ MHz} \text{ to } 1577 \text{ MHz}, T_a = 25^{\circ}\text{C} \pm 3^{\circ}\text{C})$

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Parameter	Symbol	Conditions Min Typ Max	Unit
Insertion loss *	LOSS	ANT-GPS_RX ($P_{IN} = 10.0 \text{ dBm}$) 0.32 0.55	dB
Isolation *	ISO	ANT-CDMA_TX/RX 20.0 24.0 (Correspond of ANT-GPS_RX ON) ANT-PCS_TX/RX 20.0 25.0	dB
		(Correspond of ANT-GPS_RX ON)	
Voltage standing wave ratio *	VSWR	ANT-GPS_RX 1.1 1.35	_
Control current *	I _{ctrl}	ANT-GPS_RX 0.16 9.0	μΑ
	D I GASE VIEW	ANT-GPS_RX 0.16 9.0 ANT-GPS_RX 0.16 9.0	

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■ Test Circuit



■ Logic Table

ON Course	V _{ctrl1}	V _{ctrl2}	V _{ctrl3}
ANT-CDMA_TX/RX	L	Н	L
ANT-PCS_TX/RX	Н	L	L
ANT-GPS_RX	L	L	Н

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